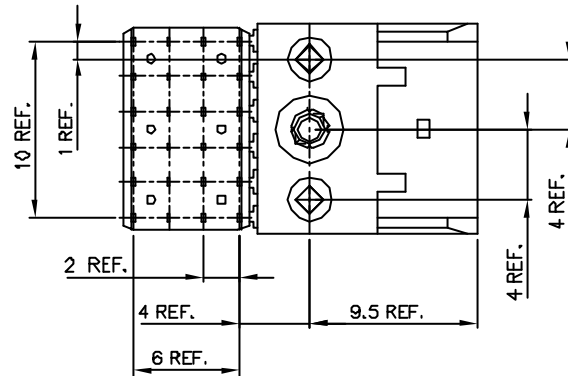
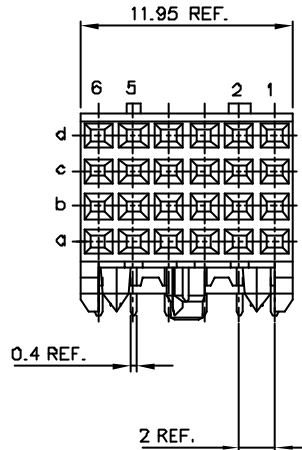
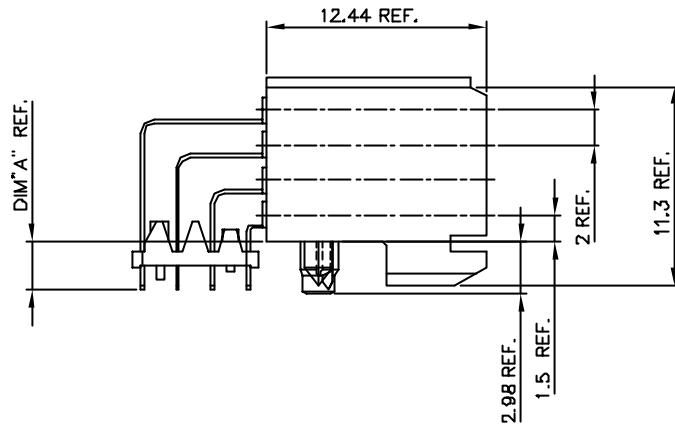
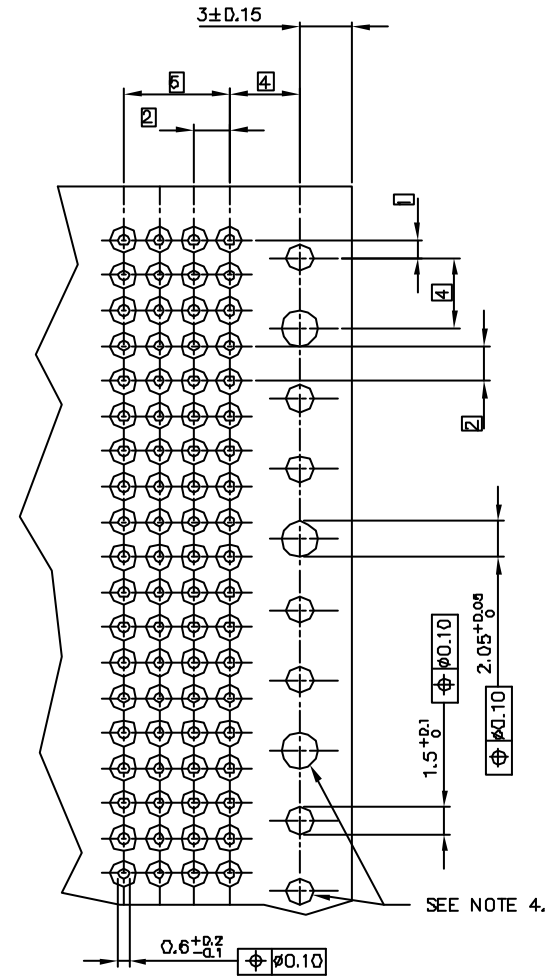
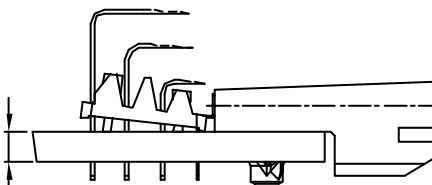


PC BOARD VERSIONS		
PRODUCTNR.	PCB THICKNESS	DIM"A"
89035-X01	1.6	2.73
89035-X11	2.4	3.53
89035-X01LF	1.6	2.73
89035-X11LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.

PC BOARD THICKNESS ±0.20
SEE TABLE



RECOMMENDED HOLE PATTERN, COMPONENT SIDE.

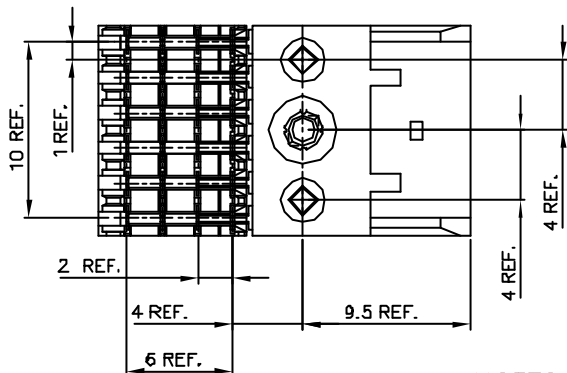
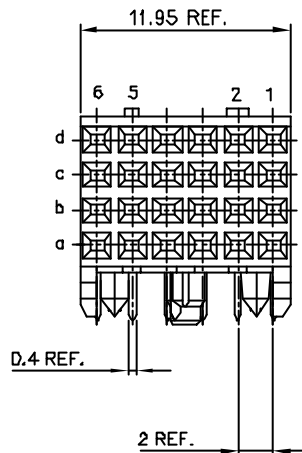
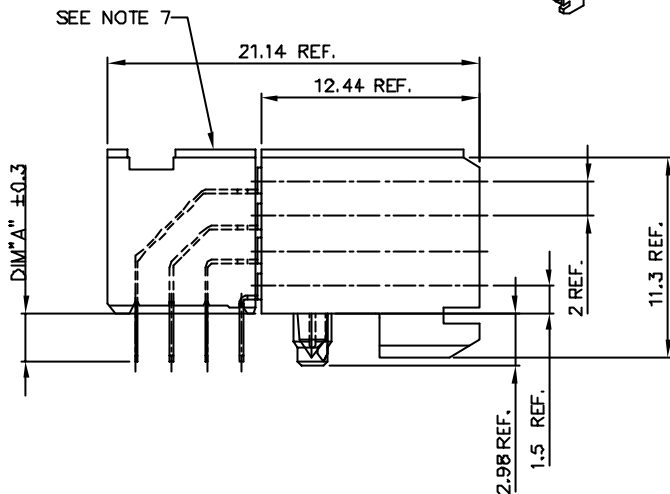
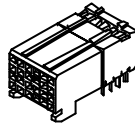
NOTES:

- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn FOR LEAD FREE .
- 4 INDICATED HOLES ARE UNPLATED.
- 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
- 6 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN CS-22-00B .
- 7 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89035-1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZLF	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZLF	0.8 µm GXT	1.3 µm Ni MIN.
89035-1YZ	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZ	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZ	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZ	0.8 µm GXT	1.3 µm Ni MIN.

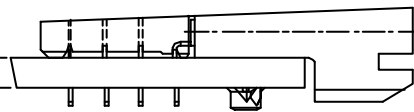
mat'l code		tolerances unless otherwise specified		CUSTOMER	
itr	ean no	dr	date	CDPY	RA F41
H	8084-0104	CU	041220	linear	projection
C	H4018	EFE	040211	angles	mm
D	H4038	008	040527	dr	H.4040100001
E	V7078	008	070602	eng	H.4040100001
F	V00078	LLA	000318	chr	H.4040100001
G	V00047	LLA	000330	appl	J.4040100001
sheet	revision	H	H	scale	A2
index	sheet	1	2	code	89035
				product family	ETRAL (tm)
				size	12 mm PRESS PEC
				code	213
				sheet	1 of 2

PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89035-X02	1.6	2.73
89035-X12	2.4	3.53
89035-X02LF	1.6	2.73
89035-X12LF	2.4	3.53

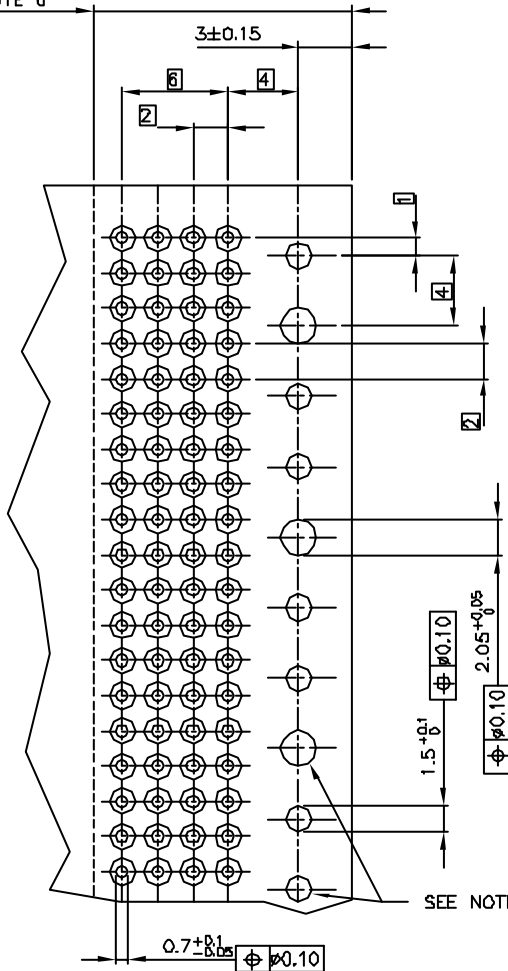


PRODUCT AFTER PC BOARD APPLICATION.

PC BOARD THICKNESS ±0.20
SEE TABLE



14.64 REF. SEE NOTE 6



RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.

NOTES:

- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS FLAME RETARDANT ACC. UL 94-V0
- TERMINAL MATERIAL: PHOSPHOR BRONZE.
- PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn
- INDICATED HOLES ARE UNPLATED.
- PRODUCT MARKING: PARTNUMBER & BATCH ID.
- SET BACK FOR PRESS BLOCK.
- TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-00B.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89035-1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZLF	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZLF	0.8 µm GXT	1.3 µm Ni MIN.
89035-1YZ	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZ	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZ	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZ	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER GDY		ELECTRONICS	
tr	san no	dr	date	linear	projection	RA FEMALE SIGNAL	
H				angles	1:1	12 mm PRESS PEG	
		dr	0. de an	mm	product form	ETRAL(um)	code
		eng	P. Scholt	070529	size	dwg no	213
		chr	P. Scholt	070529	scale	89035	sheet
		appl	001/mans	070529	8:1		2 of
sheet index	revision sheet						

This device contains unclassified information. Reproduction or communication of this information in any form is prohibited without the express written approval of the manufacturer.

All rights are reserved. Reproduction or use in any form is prohibited without the express written approval of the manufacturer.